

FIG. 1

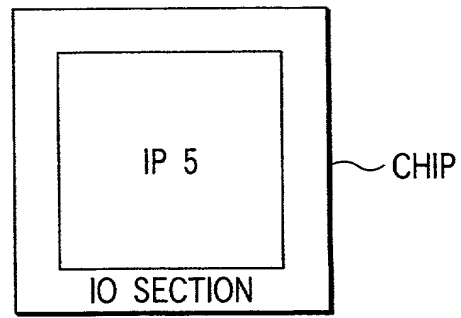
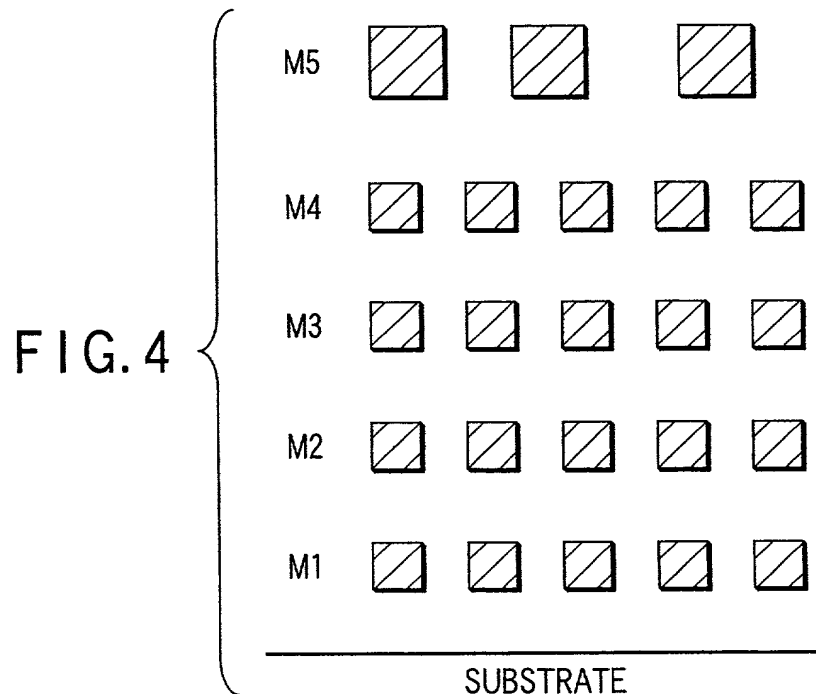
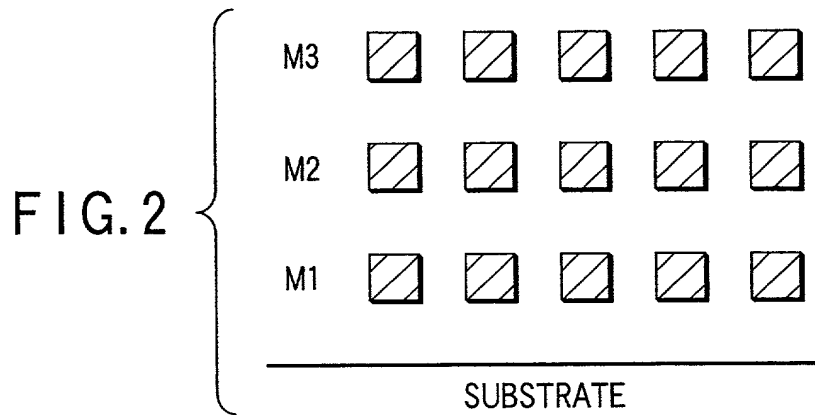


FIG. 3



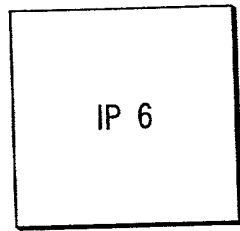


FIG. 5

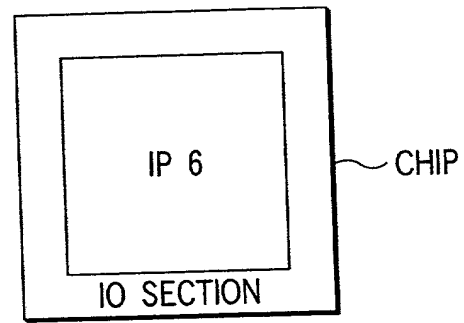
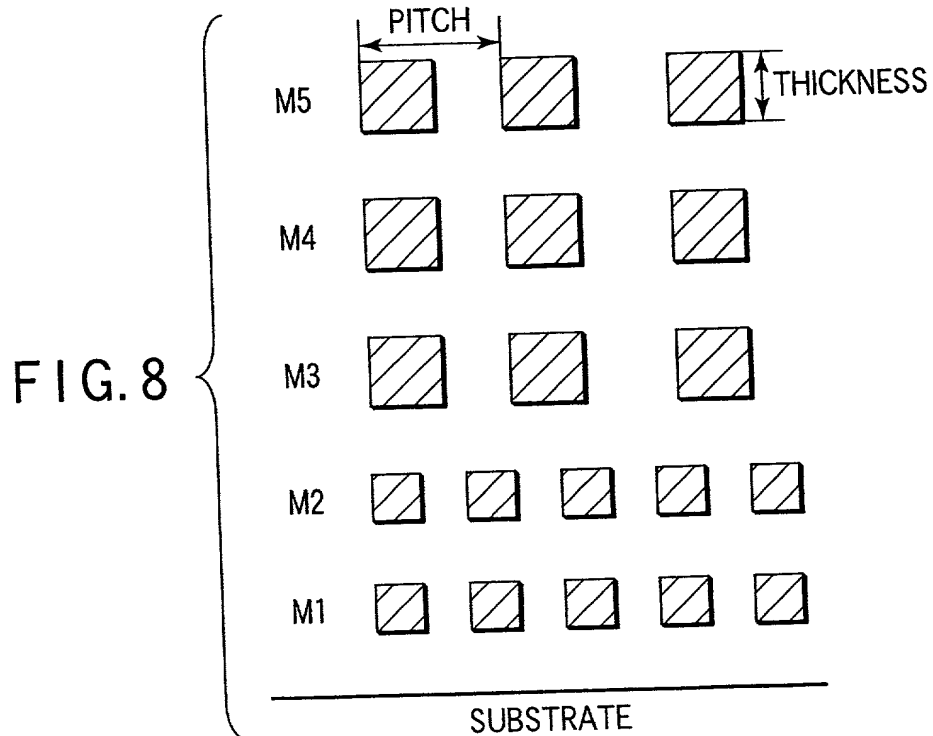
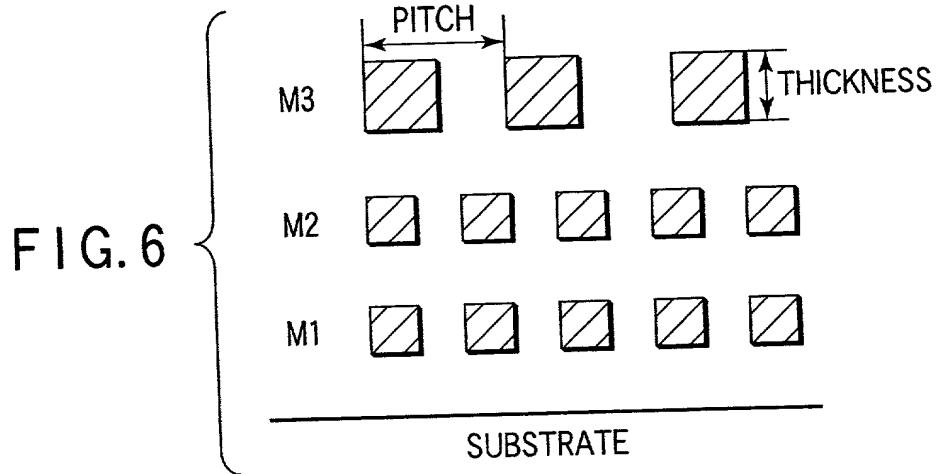


FIG. 7





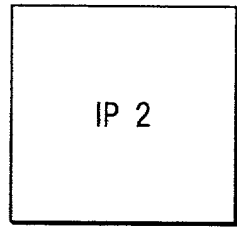


FIG. 13

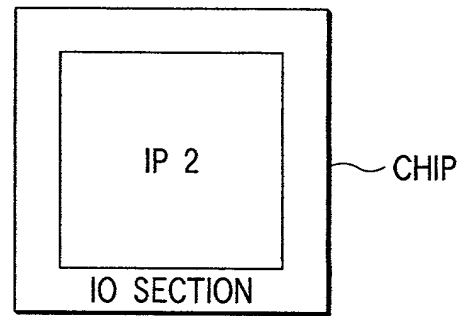
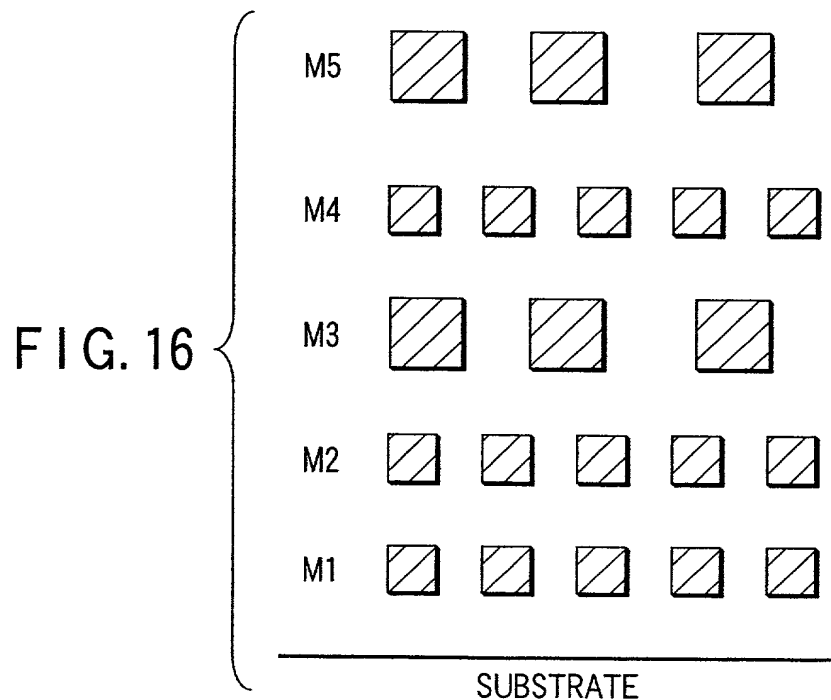
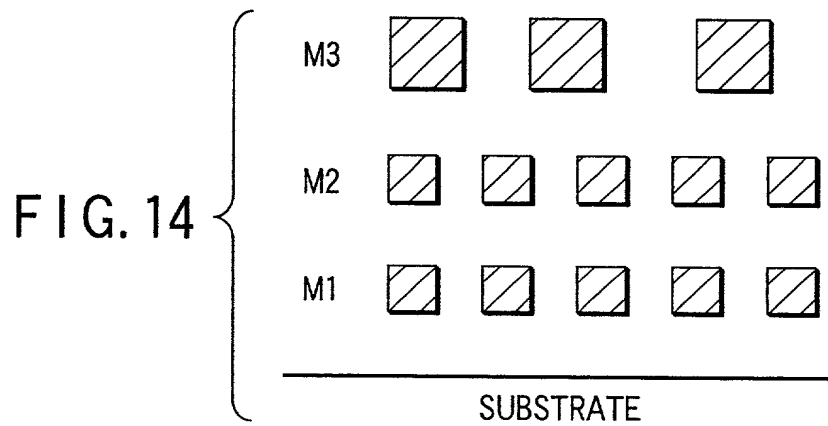


FIG. 15



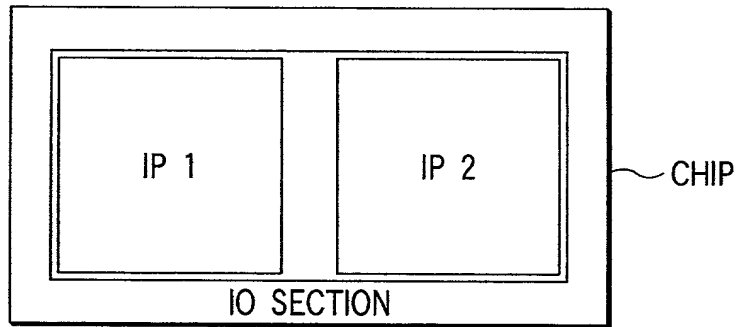


FIG. 17

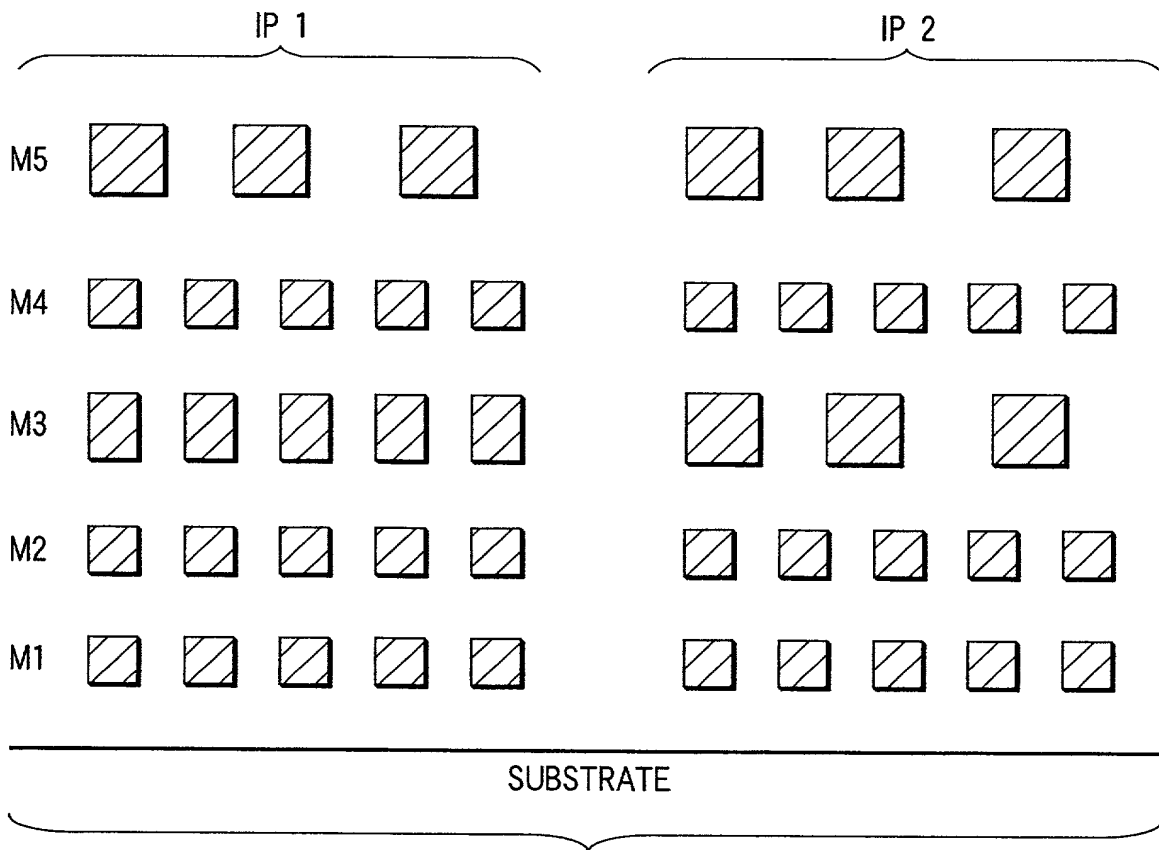


FIG. 18

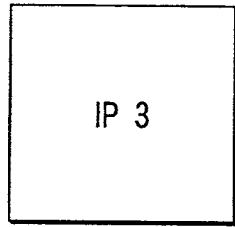


FIG. 19

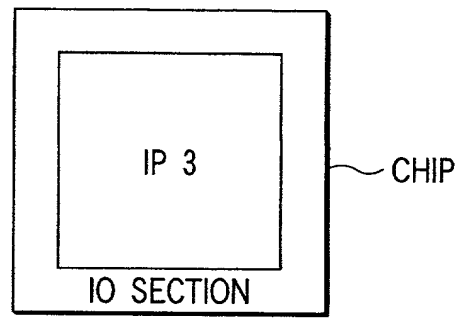
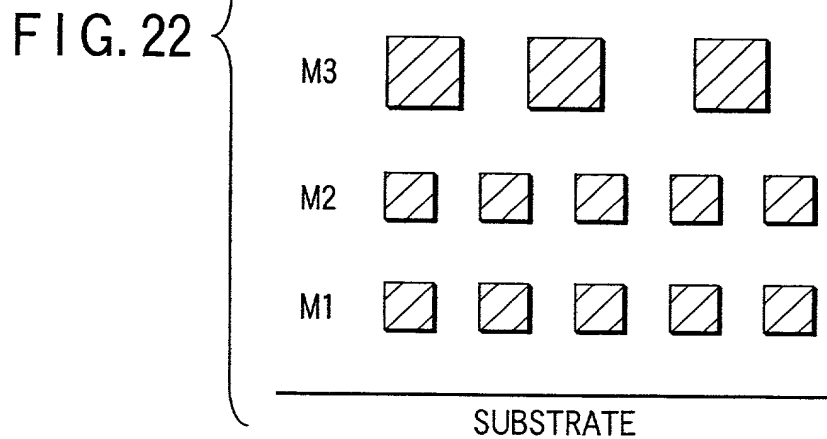
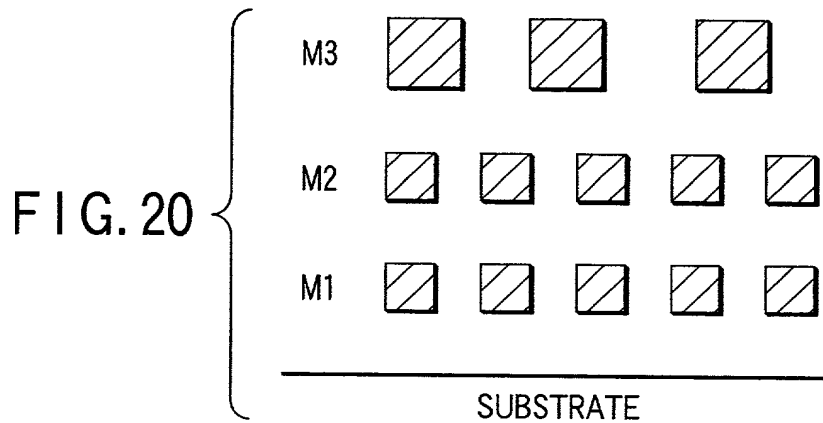


FIG. 21



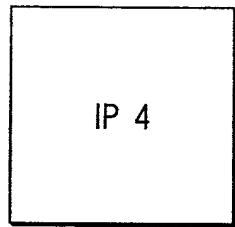


FIG. 23

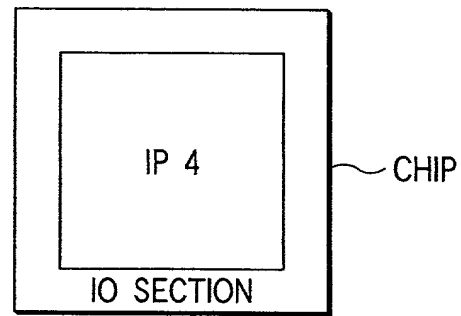
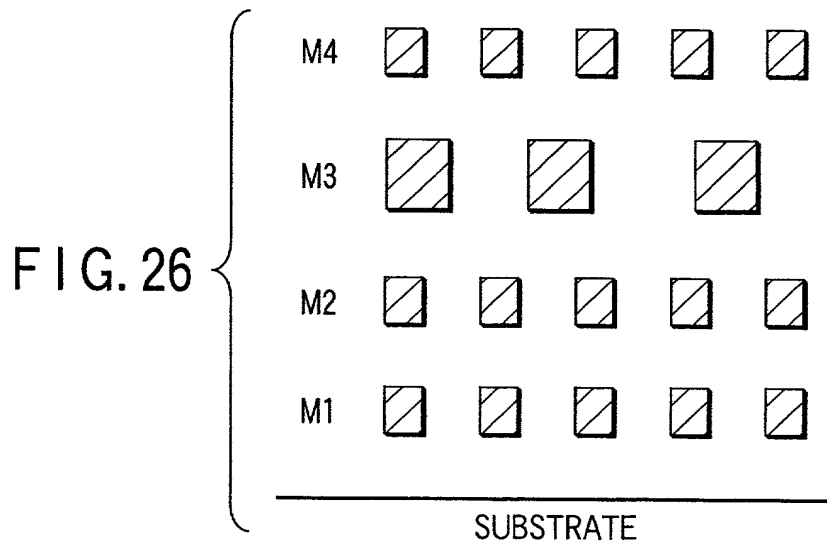
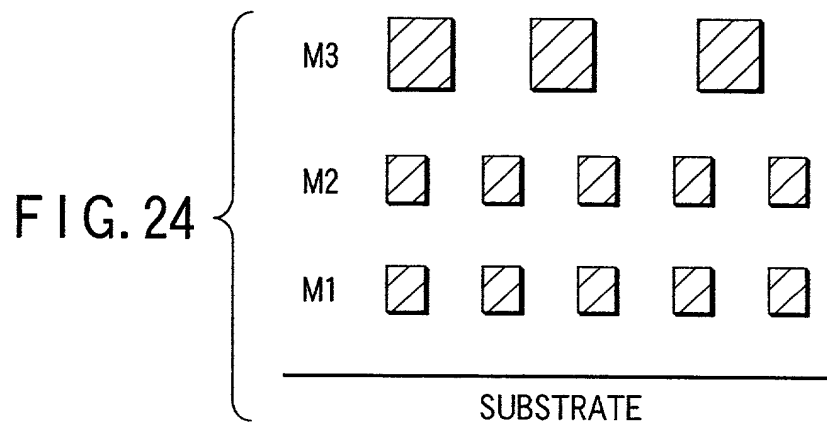


FIG. 25



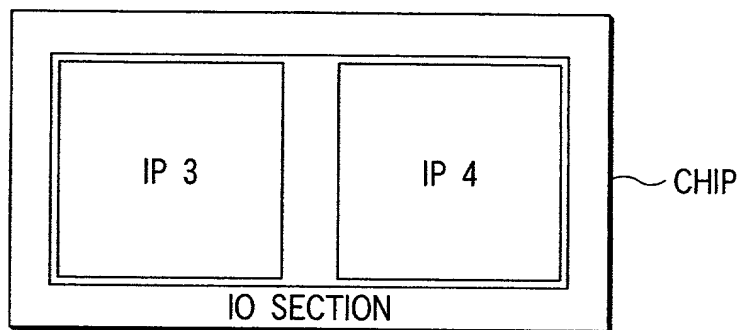


FIG. 27

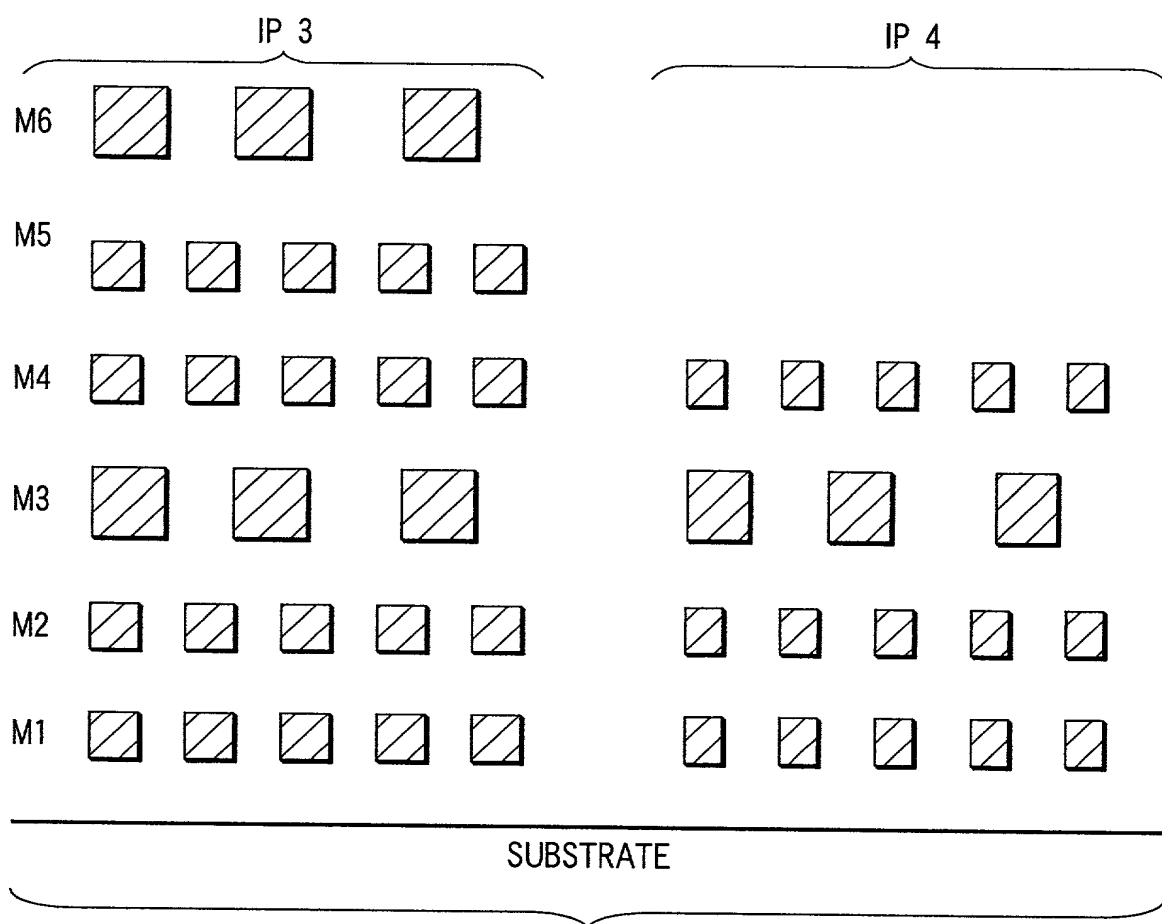


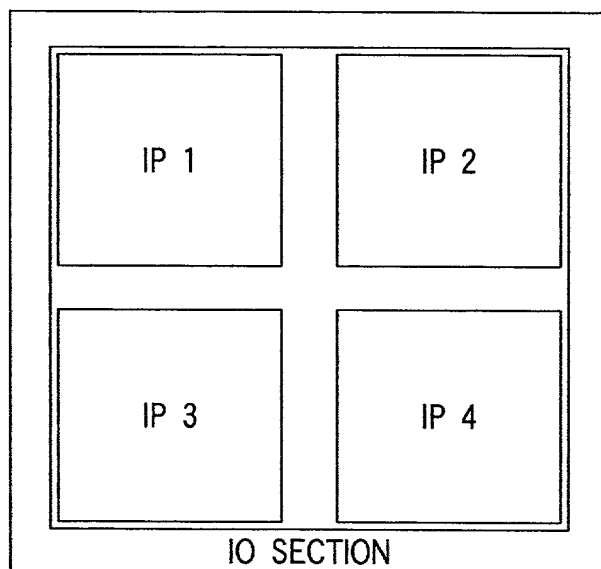
FIG. 28



	WIRING LAYER	REFERENCE EXAMPLE	PRESENT INVENTION	PURPOSE OF USING
	Mn	TK TK TK TK	TK TK	CHIP POWER SOURCE LINE
	⋮			
	Mm+2	TN TK TK TK	TN TK	SIGNAL LINE
	Mm+1	TN TN TK TK	TN TN	SIGNAL LINE
IP CORE	Mm	TN TN TN TK	TK TK	CORE POWER SOURCE LINE/ SIGNAL LINE
	⋮			
	M2	TN TN TN TN	TN TN	SIGNAL LINE
	M1	TN TN TN TN	TN TN	SIGNAL LINE

TK : THICK  
TN : THIN

FIG. 29



- IP1, IP2, IP4 :  
Mm is used as CORE power source line
- IP3 :  
Mm is used as signal line

FIG. 30